

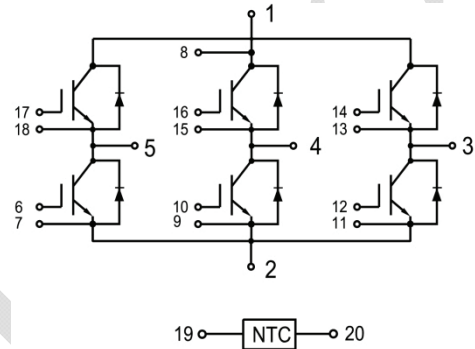
# GT150FF120A8H

## IGBT Module

### Features:

- Field Stop Trench Gate IGBT
- Short Circuit Rated > 10 $\mu$ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested (2 $\times$ I<sub>c</sub>)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement

### Circuit Diagram



### Applications:

- Industrial Inverters
- Servo Applications

### Maximum Rated Values of IGBT (T<sub>C</sub>=25°C unless otherwise specified)

V <sub>CES</sub>	Collector-Emitter Blocking Voltage		1200	V
V <sub>GES</sub>	Gate-Emitter Voltage		±20	V
I <sub>C</sub>	Continuous Collector Current	T <sub>C</sub> =100°C	150	A
		T <sub>C</sub> =25°C	220	A
I <sub>CM</sub>	Repetitive Peak Collector Current	T <sub>J</sub> =175°C	300	A
t <sub>SC</sub>	Short Circuit Withstand Time		>10	μs
P <sub>D</sub>	Maximum Power Dissipation per IGBT	T <sub>C</sub> =25°C T <sub>Jmax</sub> =150°C	710	W

## Electrical Characteristics of IGBT ( $T_C=25^\circ\text{C}$ unless otherwise specified)

### Static Characteristics

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=6\text{mA}$ , $V_{CE}=V_{GE}$	5.0	5.9	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=150\text{A}$ , $V_{GE}=15\text{V}$	$T_J=25^\circ\text{C}$	1.65	1.95	V
			$T_J=125^\circ\text{C}$	2.00		V
			$T_J=150^\circ\text{C}$	2.10		V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}$ , $V_{CE}=V_{CES}$			1	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$ , $V_{CE}=0\text{V}$			500	nA
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}$ , $V_{GE}=0\text{V}$ , $f=100\text{kHz}$		18.5		nF
$C_{oes}$	Output Capacitance			0.69		nF
$C_{res}$	Reverse Transfer Capacitance			0.23		nF

### Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600\text{V}$ , $I_C=150\text{A}$ , $R_{Gon}=10\Omega$ , $V_{GE}=\pm 15\text{V}$ , Inductive Load	$T_J=25^\circ\text{C}$		703		ns
			$T_J=125^\circ\text{C}$		700		
			$T_J=150^\circ\text{C}$		666		
$t_r$	Rise Time		$T_J=25^\circ\text{C}$		157		ns
			$T_J=125^\circ\text{C}$		165		
			$T_J=150^\circ\text{C}$		162		
$t_{d(off)}$	Turn-off Delay Time		$T_J=25^\circ\text{C}$		600		ns
			$T_J=125^\circ\text{C}$		657		
			$T_J=150^\circ\text{C}$		637		
$t_f$	Fall Time	$T_J=25^\circ\text{C}$		217		ns	
		$T_J=125^\circ\text{C}$		346			
		$T_J=150^\circ\text{C}$		360			
$E_{on}$	Turn-on Switching Loss	$V_{CC}=600\text{V}$ , $I_C=150\text{A}$ , $R_{Gon}=10\Omega$ , $V_{GE}=\pm 15\text{V}$ , $di/dt=790\text{A}/\mu\text{s}$ ( $T_J=150^\circ\text{C}$ ) Inductive Load	$T_J=25^\circ\text{C}$		14.1		mJ
			$T_J=125^\circ\text{C}$		17.4		
			$T_J=150^\circ\text{C}$		17.6		

E <sub>off</sub>	Turn-off Switching Loss	V <sub>CC</sub> =600V, I <sub>C</sub> =150A, R <sub>Goff</sub> =10Ω, V <sub>GE</sub> =±15V, du/dt=4890V/μs ( T <sub>J</sub> =150°C) Inductive Load	T <sub>J</sub> =25°C	12.0	mJ
			T <sub>J</sub> =125°C	15.5	
			T <sub>J</sub> =150°C	15.9	
Q <sub>g</sub>	Total Gate Charge	V <sub>GE</sub> =+15V...-15V	T <sub>J</sub> =25°C	1.48	μC
R <sub>g internal</sub>	Internal Gate Resistance		T <sub>J</sub> =25°C	3	Ω
RBSOA	I <sub>C</sub> =300A, V <sub>CC</sub> =1050V, V <sub>p</sub> =1200V, R <sub>Goff</sub> = 10Ω, V <sub>GE</sub> =+15V to 0V, T <sub>J</sub> =125°C			Trapezoid	
I <sub>SC</sub>	V <sub>GE</sub> =± 15V, V <sub>CC</sub> =600V, R <sub>Gon</sub> =10Ω, R <sub>Goff</sub> =10Ω, tp=10us, T <sub>J</sub> =125°C Inductive Load			1140	A
R <sub>θJC</sub>	IGBT Thermal Resistance: Junction-to-Case(per IGBT)			0.175	°C/W

### Maximum Rated Values of Diode (T<sub>C</sub>=25°C unless otherwise specified)

V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	1200	V
I <sub>F</sub>	Diode Continuous Forward Current	150	A
I <sub>FM</sub>	Diode Maximum Forward Current	300	A

### Electrical Characteristics of Diode (T<sub>C</sub>=25°C unless otherwise specified)

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
V <sub>FM</sub>	Forward Voltage	I <sub>F</sub> =150A	T <sub>J</sub> =25°C	1.90		V
			T <sub>J</sub> =125°C	2.05		
			T <sub>J</sub> =150°C	2.05		
I <sub>rr</sub>	Peak Reverse Recovery Current	I <sub>F</sub> =150A, di/dt=1020A/μs (T <sub>J</sub> =150°C), V <sub>rr</sub> =600V, V <sub>GE</sub> =±15V	T <sub>J</sub> =25°C	85.9		A
			T <sub>J</sub> =125°C	109.4		
			T <sub>J</sub> =150°C	118.8		
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =150A, di/dt=1020A/μs (T <sub>J</sub> =150°C), V <sub>rr</sub> =600V, V <sub>GE</sub> =±15V	T <sub>J</sub> =25°C	246		ns
			T <sub>J</sub> =125°C	446		
			T <sub>J</sub> =150°C	480		
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =150A, di/dt=1020A/μs (T <sub>J</sub> =150°C), V <sub>rr</sub> =600V, V <sub>GE</sub> =±15V	T <sub>J</sub> =25°C	12.1		μC
			T <sub>J</sub> =125°C	22.8		
			T <sub>J</sub> =150°C	26.2		

E <sub>rec</sub>	Reverse Recovery Energy	I <sub>F</sub> =150A, di/dt=1020A/μs (T <sub>J</sub> =150°C), V <sub>rr</sub> =600V, V <sub>GE</sub> =±15V	T <sub>J</sub> =25°C	5.3	mJ
			T <sub>J</sub> =125°C	10.2	
			T <sub>J</sub> =150°C	12.3	
R <sub>θJC</sub>	Diode Thermal Resistance: Junction-to-Case			0.259	°C/W

### Internal NTC-Thermistor Characteristics

R <sub>25</sub>	T <sub>C</sub> =25°C	5		kΩ
ΔR/R	T <sub>C</sub> =100°C, R <sub>100</sub> =481Ω		±5	%
P <sub>25</sub>	T <sub>C</sub> =25°C	50		mW
B <sub>25/50</sub>	R <sub>2</sub> =R <sub>25</sub> exp[B <sub>25/50</sub> (1/T <sub>2</sub> -1/(298.15K))]	3380		K
B <sub>25/80</sub>	R <sub>2</sub> =R <sub>25</sub> exp[B <sub>25/80</sub> (1/T <sub>2</sub> -1/(298.15K))]	3440		K

### Module

Symbol	Description	Min.	Typ.	Max.	Units
V <sub>ISO</sub>	Isolation Voltage (All Terminals Shorted)	f=50Hz, 1minute	2500		V
Internal Isolation		Al <sub>2</sub> O <sub>3</sub>			
d <sub>creep</sub>	Creepage Distance: Terminal to Baseplate			25	mm
	Creepage Distance: Terminal to Terminal			12.5	mm
d <sub>clear</sub>	Clearance Distance: Terminal to Baseplate			11	mm
	Clearance Distance: Terminal to Terminal			7	mm
L <sub>SCE</sub>	Stray Inductance Module	Measured between terminals 2 and 3		20	nH
T <sub>J</sub>	Maximum Junction Temperature			150	°C
T <sub>JOP</sub>	Maximum Operating Junction Temperature Range		-40	+150	°C
T <sub>stg</sub>	Storage Temperature		-40	+125	°C
CTI	Comparative Tracking Index		200		
R <sub>θCS</sub>	Case-to-Sink Thermally (Conductive Grease Applied)			0.03	°C/W
M	Power Terminals Screw:M5		3.0	6.0	N·m
M	Mounting Screw:M6		3.0	6.0	N·m
G	Weight			390	g

## Ordering Information Table

Device code	G	T	150	FF	120	A8	H
	①	②	③	④	⑤	⑥	⑦

- ① - IGBT Module
- ② - Trench, Low Switching Losses IGBT
- ③ - Rated Current (150=150A)
- ④ - Circuit Configuration (Full Bridge)
- ⑤ - Rated Voltage (120=1200V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)

SilverMicro

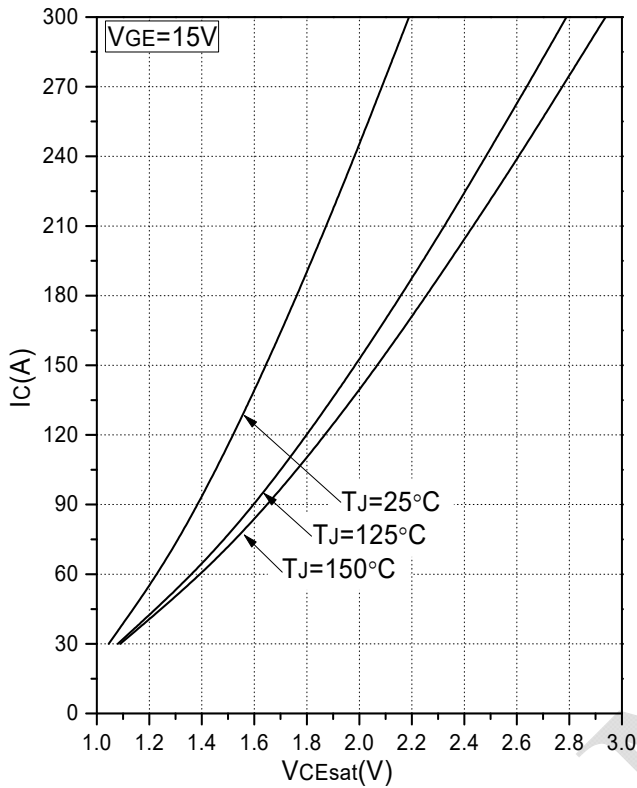


Fig.1 Typical Saturation Voltage Characteristics

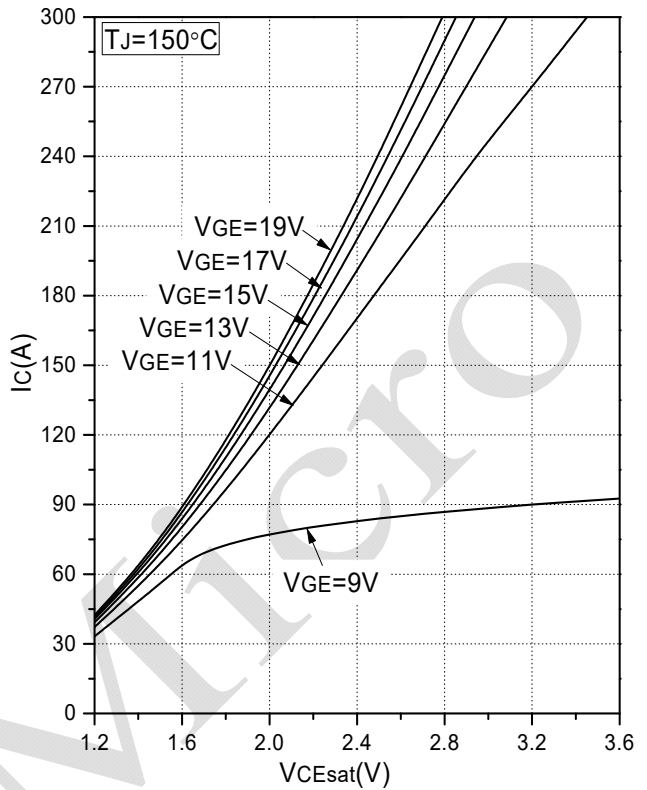


Fig.2 Typical Output Characteristics

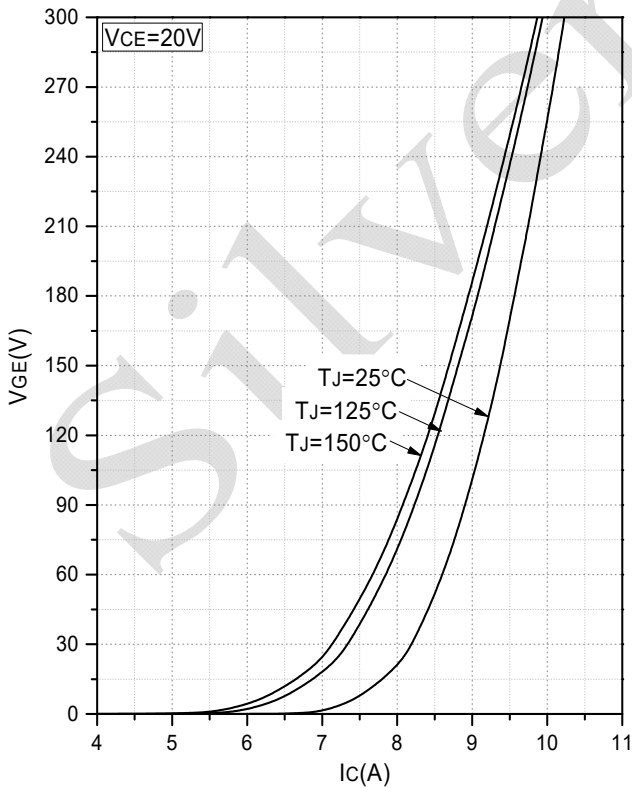


Fig.3 Transfer Characteristic

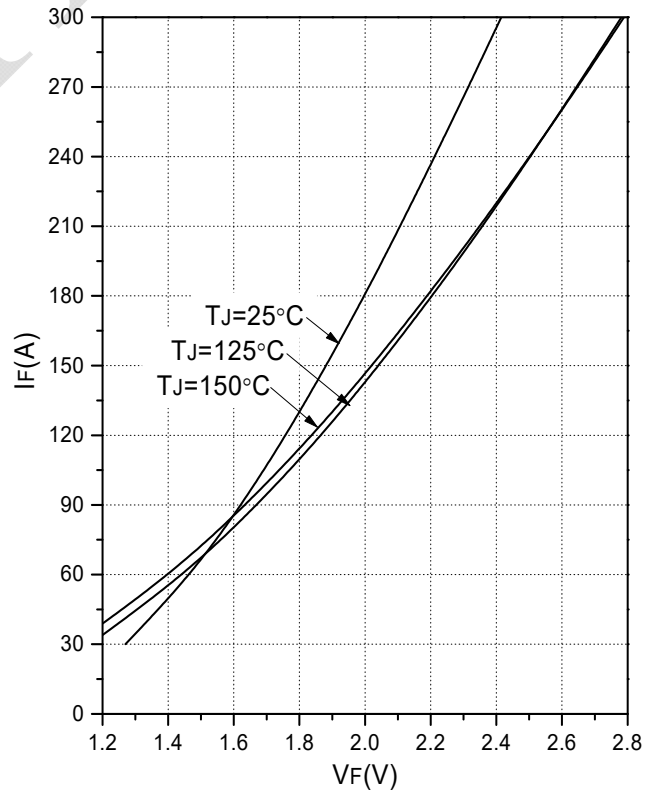


Fig.4 Forward Characteristics of Diode

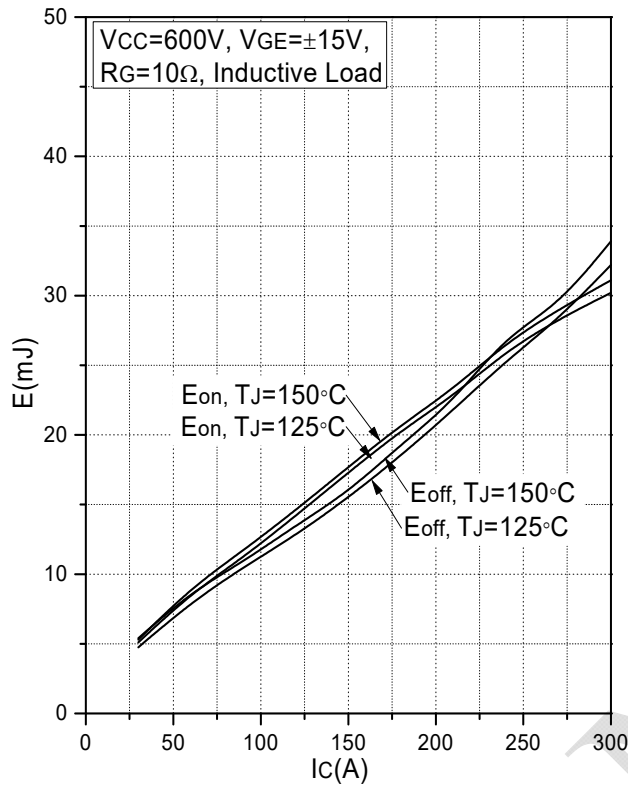


Fig.5 Typical Switching Loss vs. Collector Current

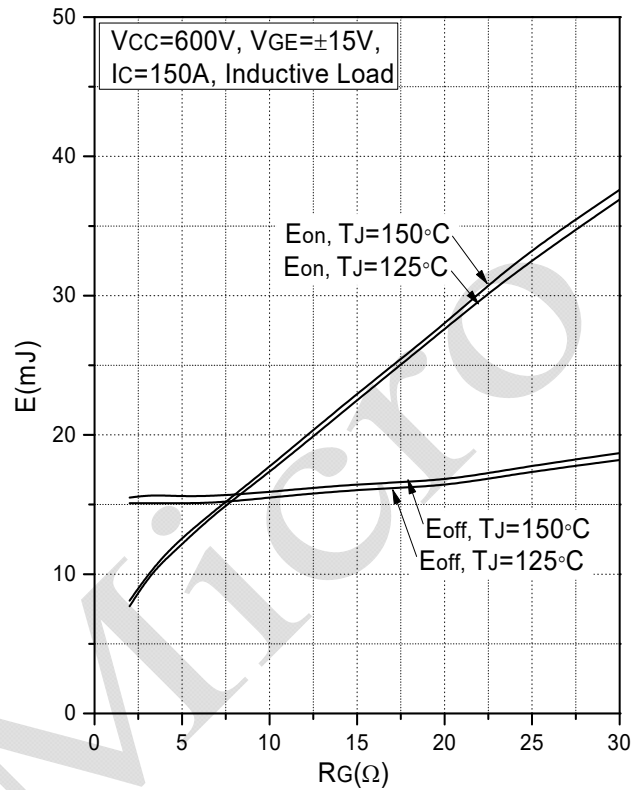


Fig.6 Typical Switching Loss vs. Gate Resistance

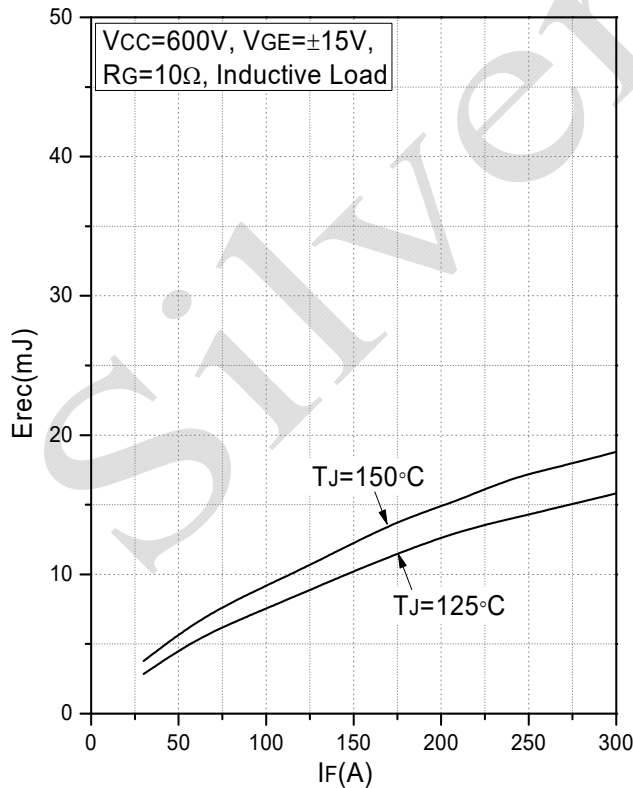


Fig.7 Typical Switching Loss vs. Forward Current

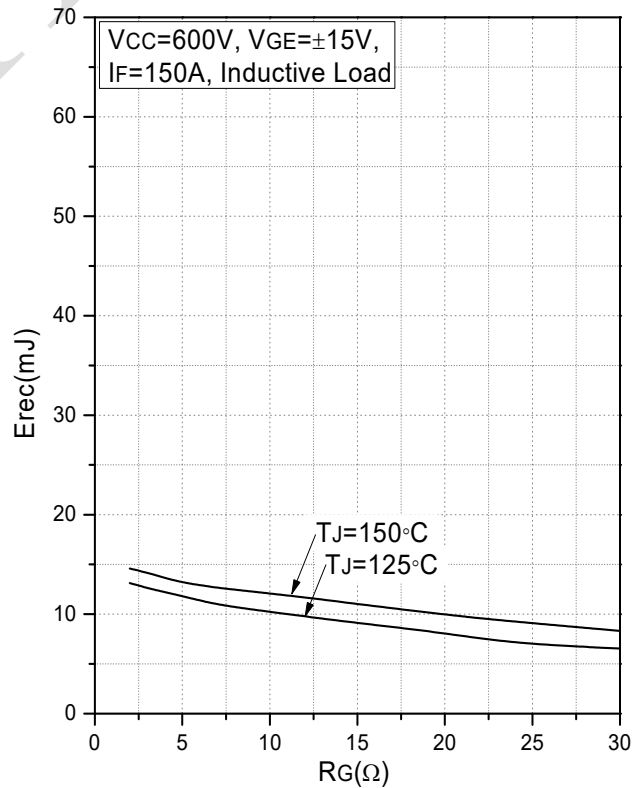


Fig.8 Typical Switching Loss vs. Gate Resistance

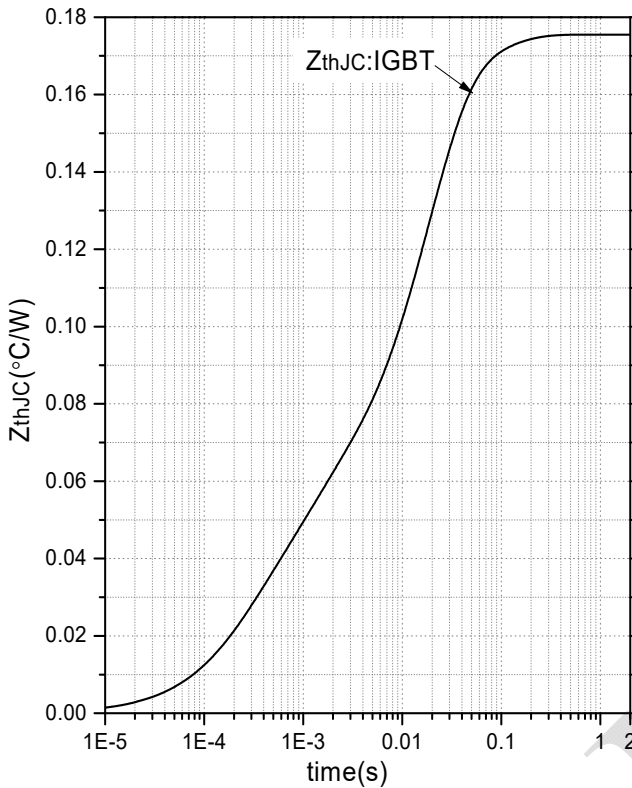


Fig.9 Transient Thermal Impedance of IGBT

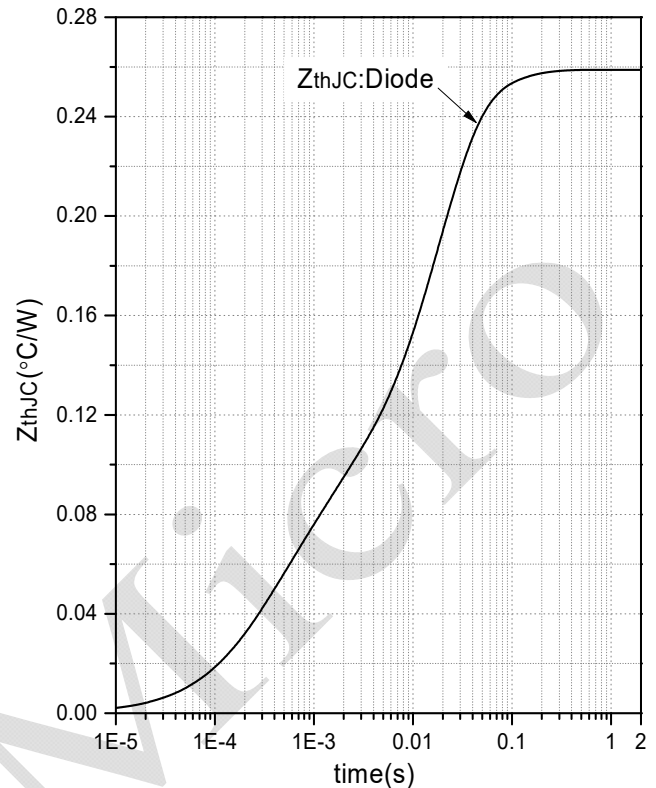


Fig.10 Transient Thermal Impedance of Diode

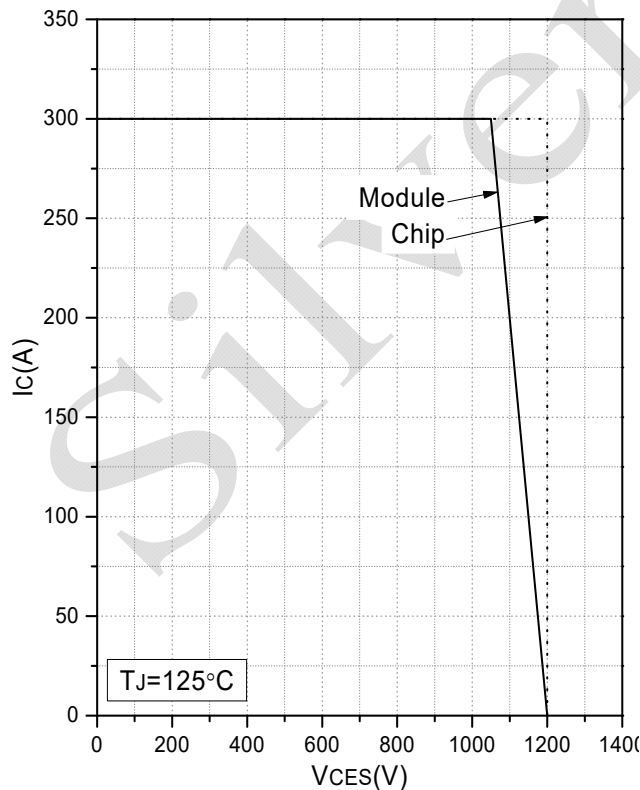


Fig.11 Reverse Bias Safe Operation Area

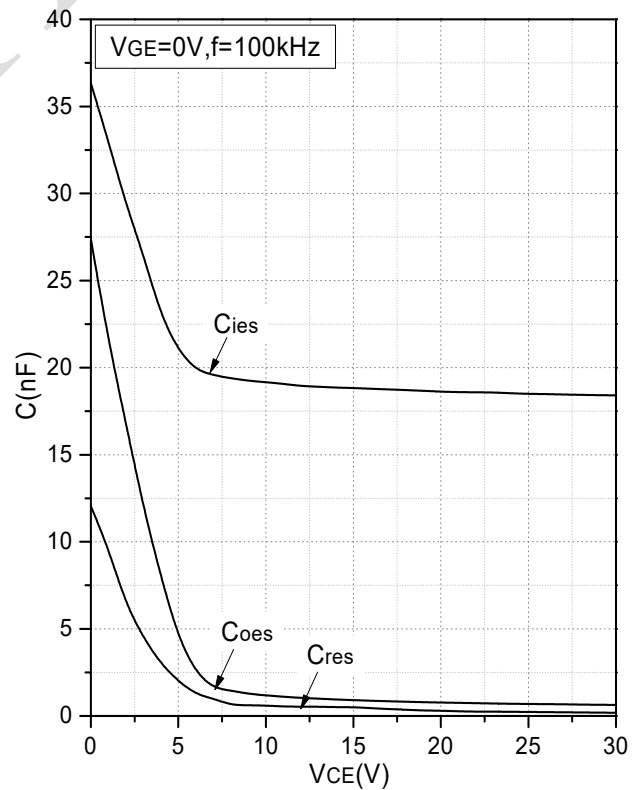


Fig.12 Capacitance Characteristics



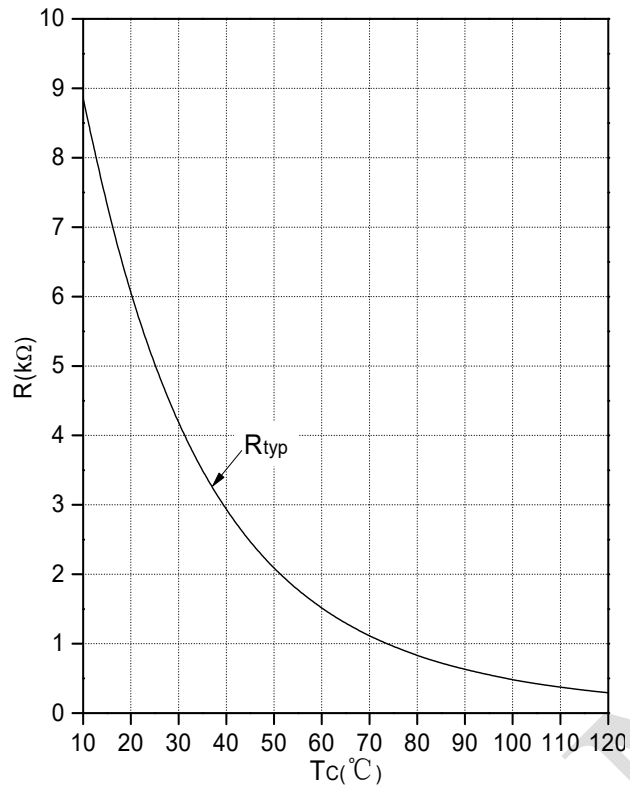
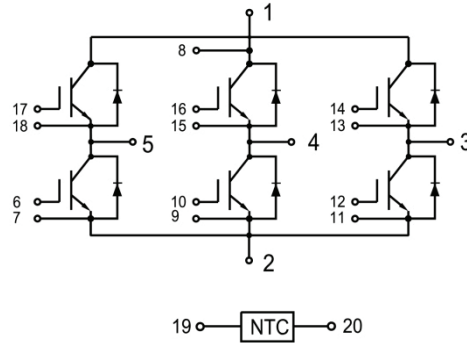
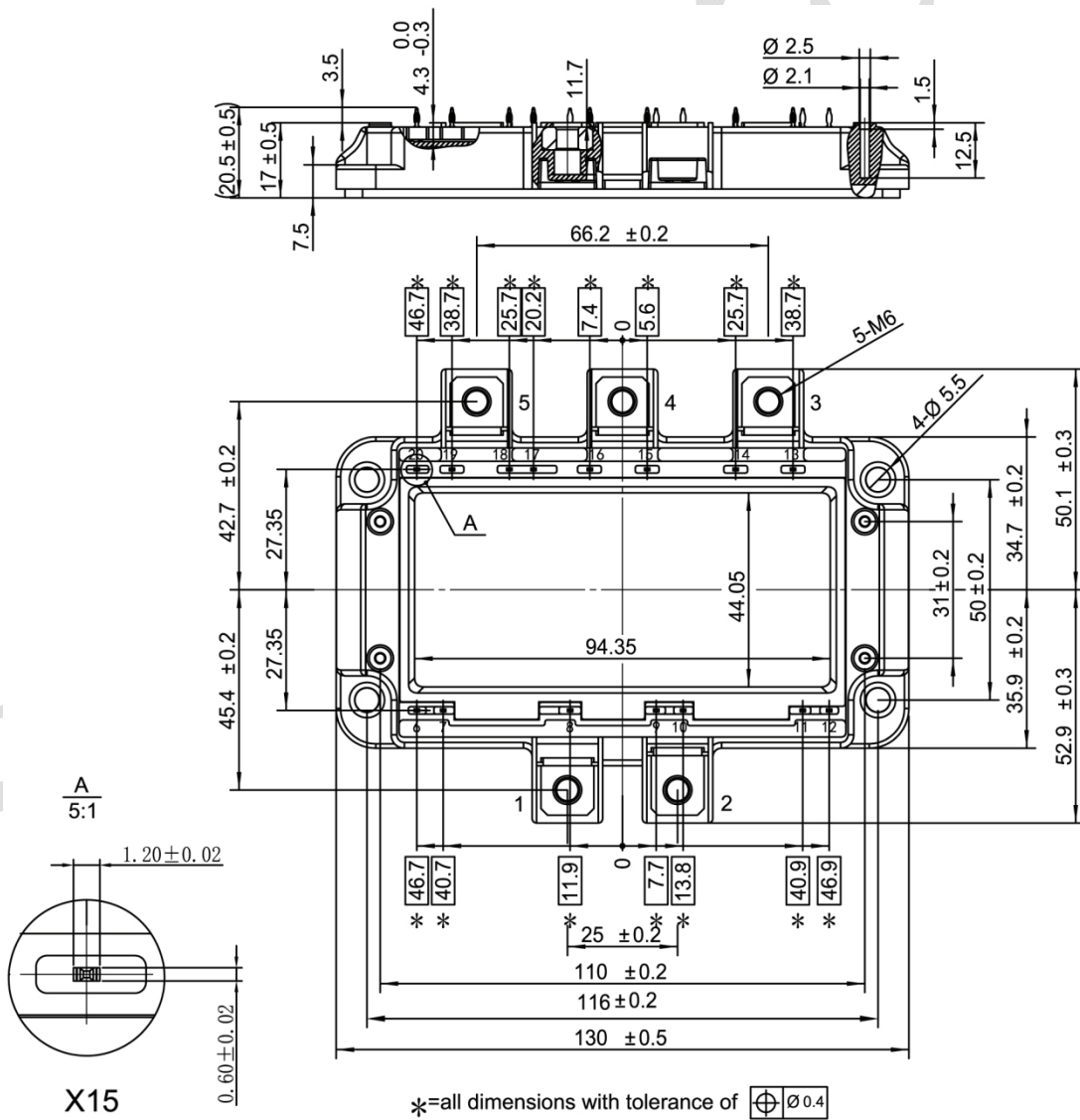


Fig.13 NTC Temperature Characteristics

### Internal Circuit



### Package Outline (Unit: mm):



Date	Revision	Notes
11/29/2022	A	Final Version

## Announcement

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